

	Type	L #	Hits	Search Text	DBs
1	BRS	L1	235	257/737.ccls.	EPO; JPO; IBM_TDB
2	BRS	L2	1737	257/737.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	1647	257/738.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	2402	257/778.ccls.	US-PGPUB; USPAT; USOCR
5	BRS	L5	1214	257/780.ccls.	US-PGPUB; USPAT; USOCR
6	BRS	L6	1102	257/750.ccls.	US-PGPUB; USPAT; USOCR
7	BRS	L7	2883	257/758.ccls.	US-PGPUB; USPAT; USOCR
8	BRS	L8	834	257/779.ccls.	US-PGPUB; USPAT; USOCR
9	BRS	L9	2087	257/774.ccls.	US-PGPUB; USPAT; USOCR
10	BRS	L10	2336	chip adj scale adj package	US-PGPUB; USPAT
11	BRS	L11	2336	chip adj scale adj package	US-PGPUB; USPAT; USOCR
12	BRS	L12	129	257/778.ccls.	EPO; JPO; IBM_TDB
13	BRS	L13	238	257/779.ccls.	EPO; JPO; IBM_TDB
14	BRS	L14	98	257/780.ccls.	EPO; JPO; IBM_TDB
15	BRS	L15	494	257/758.ccls.	EPO; JPO; IBM_TDB
16	BRS	L16	0	((insulating adj layer) and (metal adj stack) and solder and contact).clm.	US-PGPUB
17	BRS	L17	5	((insulating adj layer) and metal and stack and solder and contact).clm.	US-PGPUB